MIC-733-TS

NEMA TS2 AI Inference System Based on NVIDIA® Jetson AGX Orin™

Features

- Compact fanless design
- Embedded with NVIDIA® Jetson AGX Orin™
- NEMA TS2 compliance
- -34 to 74°C operating temperature support
- 500ms power interruption backup (Based on NEMA TS2)

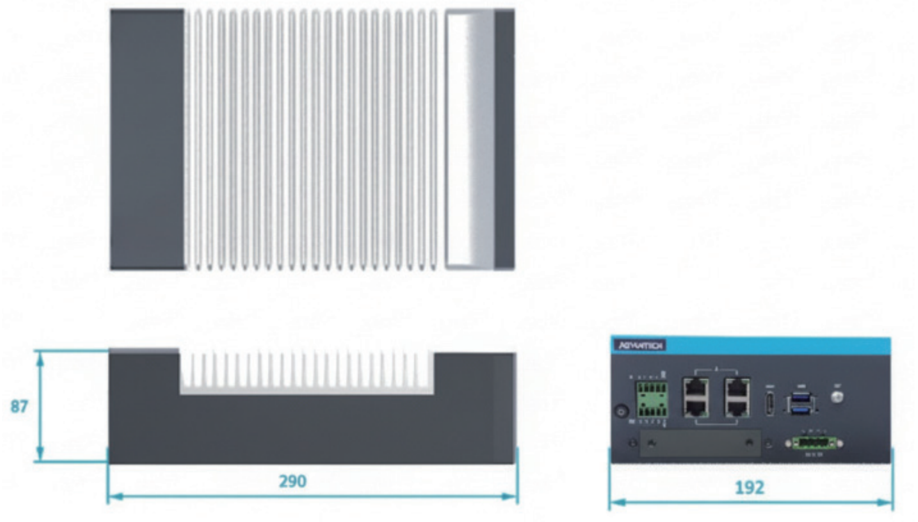
Specifications

		NVIDIA® Jetson AGX Orin™
Processor	NVIDIA Jetson Series	AGX Orin 32G
	CPU	8-core NVIDIA Arm® Cortex A78AE v8.2 64-bit CPU, 2MB L2 + 4MB L3
	GPU	1792-core NVIDIA Ampere GPU with 56 Tensor Cores, Maximum Operating Frequency: 930 MHz
	AI Performance Reference	Up to 200 TOPs
	Memory	32GB 256-bit LPDDR5 DRAM
I/O	Ethernet	4 x 10/100/1000 Mbps (Support 4 x Gigabit PoE/2 Gigabit PoE+ with 60W power budget)
	Display	HDMI (Max. resolution 3840x2160 @ 60Hz)
	USB	2 x USB 3.0
	Digital I/O	4-ch DI, 4-ch DO
	Power Switch	1 x Power ON/OFF Button
	Serial Ports	2 x RS-232/422/485 (On-board pin header)
	OTG USB	1 x Micro USB
Expansion	Mini PCIe	2 x mPCIe (Signal: PCIe+USB)
	SIM	2 x Nano SIM slots
	M.2	1 x M.2 3052 (B-Key, Signal: USB)
	TPM (Optional)	1 x TPM 2.0
	iDoor (Optional)	1 x iDoor bracket reserve
Storage	M.2	1 x M.2 2280 M-Key Slot, pre-installed NVMe with 512G 3D TLC BiCS5 (-40~85°C)
	SD Card	1 x Micro SD slot
Power	Mode	AT/ATX (Default AT)
	Input Voltage	12 VDC (With external 240W Adapter) (pre-configured with hardened power adaptor/power core)
Environment	Operating Temperature	-34 ~ +74 °C with 0.7 m/s airflow (in 30W AGX Orin mode)
	Operating Humidity	95% @ 40 °C (non-condensing)
	Vibration	3Grms @ 5 ~ 500 Hz, random, 1 hr/axis
	Shock	10G / 11 ms
Mechanical	Dimensions (W x D x H)	192 x 290 x 87 mm
	Weight	4.5 kg (9.9 lb)
	Installation	Desktop / Wall mount
BSP	Jetpack	Above 6.0
Certifications		NEMA-TS2/CE/FCC (No RED certification)

* Depending on the installation conditions and interface connections, it is possible for performance derating for cellular LTE module and the MAXN mode of AGX Orin in the maximum operating temperature, as for the wireless module application, please check the its user documentation first.

Dimensions

Unit: mm [inch]



Ordering Information

Part Number	NVIDIA Module	Memory	eMMC
MIC-733-TS5A1	AGX Orin System with NEMA TS2 Compliance	32 GB	64 GB

Optional

Part Number	Description
1700029019-01	Power Cord (PSE/BSMI), 3-pin, 7A, 125V, 1.8 M, DAC-ST01
1702002605	Power Cord (EU) 2-pin, 10/16A, 220V, 1.83 M, 90 D
1702002600	Power Cord UL 3P 10A 125V 183cm
1960065854N001	PCM series module bracket
98R2711AL00	Allxon OOB Bolt module
PCA-TPMSPI-00A1	TPM 2.0 Module by SPI interface
1700019968	F Cable15CM 2x10P-2.0/D-SUB 9P for 2 COM ports
1960068789T008	IDOOR COMX2 Cover for 2 COM ports

Remote Management Enrollment

Enroll in 24/7 secure service to get all the features of remote device management on one centralized cloud portal - Allxon Portal.

*Supports JetPack 4.4 GA and above

Enrollment Page: https://allxon.com/jetson/device_enroll/